BAT54CTT1G, SBAT54CTT1G

Dual Series Schottky Barrier Diodes

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

Features

- Extremely Fast Switching Speed
- Low Forward Voltage 0.35 Volts (Typ) @ $I_F = 10 \text{ mAdc}$
- AEC Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS ($T_J = 125$ °C unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	30	V
Forward Power Dissipation @ T _A = 25°C Derate above 25°C	P _F	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	555	°C/W
Forward Current (DC)	ΙF	200 Max	mA
Non-Repetitive Peak Forward Current, t _p < 10 msec	I _{FSM}	600	mA
Repetitive Peak Forward Current Pulse Wave = 1 sec, Duty Cycle = 66%	I _{FRM}	300	mA
Junction Temperature	T _J	-55 to 125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



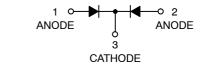
ON Semiconductor®

http://onsemi.com

30 VOLT DUAL COMMON CATHODE SCHOTTKY BARRIER DIODES



SC-75 CASE 463 STYLE 3



MARKING DIAGRAM



5C = Device Code M = Date Code* ■ Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
BAT54CTT1G	SC-75 (Pb-Free)	3,000 / Tape & Reel
SBAT54CTT1G	SC-75 (Pb-Free)	3,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

1

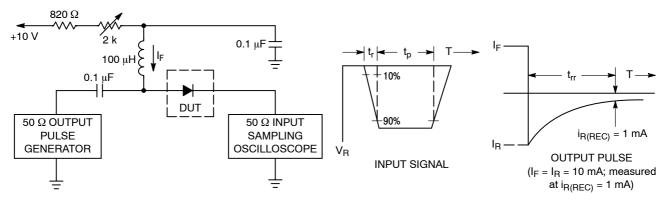
FR-4 board with minimum mounting pad.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

BAT54CTT1G, SBAT54CTT1G

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (EACH DIODE)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I _R = 10 μA)	V _{(BR)R}	30	-	-	V
Total Capacitance (V _R = 1.0 V, f = 1.0 MHz)	C _T	-	7.6	10	pF
Reverse Leakage (V _R = 25 V)	I _R	-	0.5	2.0	μAdc
Forward Voltage (I _F = 0.1 mAdc)	V _F	_	0.22	0.24	Vdc
Forward Voltage (I _F = 30 mAdc)	V _F	-	0.41	0.5	Vdc
Forward Voltage (I _F = 100 mAdc)	V _F	_	0.52	0.8	Vdc
Reverse Recovery Time $(I_F = I_R = 10 \text{ mAdc}, I_{R(REC)} = 1.0 \text{ mAdc}, Figure 1)$	t _{rr}	-	-	5.0	ns
Forward Voltage (I _F = 1.0 mAdc)	V _F	-	0.29	0.32	Vdc
Forward Voltage (I _F = 10 mAdc)	V _F	-	0.35	0.40	Vdc



Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA.

- 2. Input pulse is adjusted so $I_{\mbox{\scriptsize R(peak)}}$ is equal to 10 mA.
- 3. t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

BAT54CTT1G, SBAT54CTT1G

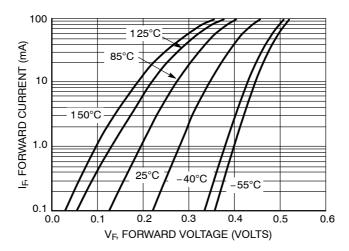


Figure 2. Forward Voltage

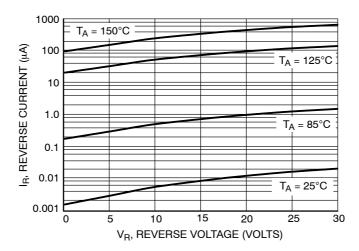


Figure 3. Leakage Current

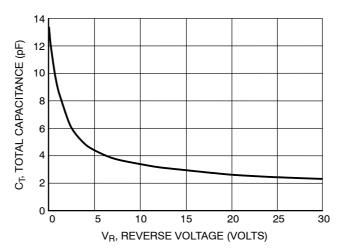
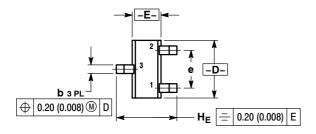


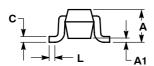
Figure 4. Total Capacitance

BAT54CTT1G, SBAT54CTT1G

PACKAGE DIMENSIONS

SC-75 / SOT-416 CASE 463-01 **ISSUE F**



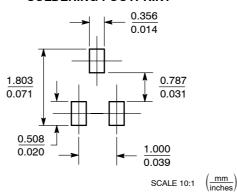


- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.70	0.80	0.90	0.027	0.031	0.035
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.15	0.20	0.30	0.006	0.008	0.012
С	0.10	0.15	0.25	0.004	0.006	0.010
D	1.55	1.60	1.65	0.059	0.063	0.067
E	0.70	0.80	0.90	0.027	0.031	0.035
е	1.00 BSC		0.04 BSC			
L	0.10	0.15	0.20	0.004	0.006	0.008
HE	1.50	1.60	1.70	0.061	0.063	0.065

STYLE 3: PIN 1. ANODE 2. ANODE 3. CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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